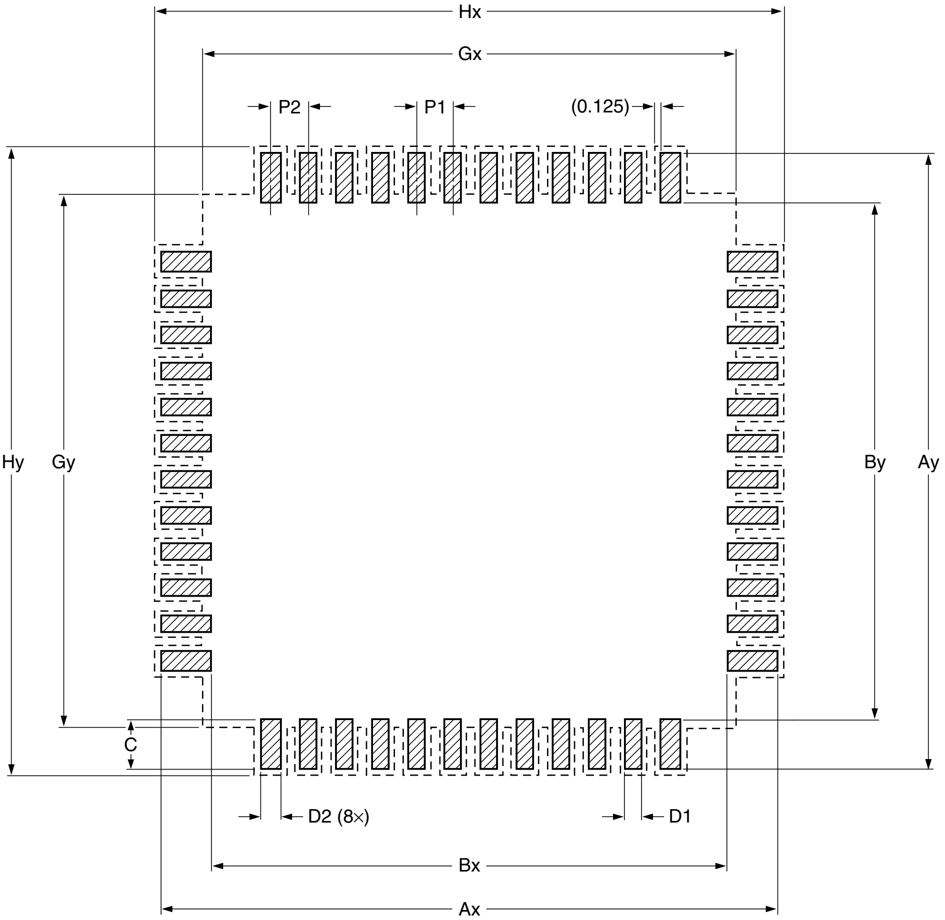
Reflow soldering footprint

Footprint information for reflow soldering of LQFP48 package **SOT313-2**



Generic footprint pattern

Refer to the package outline drawing for actual layout

▨ solder land

- - - - occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	10.350	10.350	7.350	7.350	1.500	0.280	0.500	7.500	7.500	10.650	10.650

sot313-2_fr

www.nxp.com

© 2010 NXP B.V.
All rights reserved. Reproduction in whole or in part is prohibited without prior consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of it's use. Publication thereof does not convey or imply any license under patent- or other industrial or intellectual property rights.

Printed in the Netherlands